

TPS3809x 3-Pin Supply Voltage Supervisors

1 Features

- 3-pin SOT-23 package
- Supply current of 9 µA (typical)
- Precision supply voltage monitor 2.5 V, 3 V, 3.3 V, 5 V
- Pin-for-pin compatible with MAX 809
- Temperature range: -40°C to +85°C

2 Applications

- **Factory automation**
- Wireless speakers
- Motor drives
- Servers
- **Appliances**
- **Electricity meters**
- **Building automation**

3 Description

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems. The newer TLV809E device is an alternative with the same pins, functions and electrical parameters.

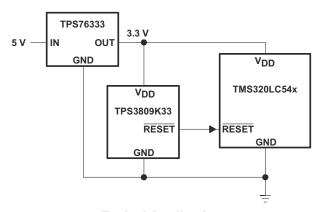
During power-on, RESET is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors V_{DD} and keeps RESET active as long as V_{DD} remains below the threshold voltage VIT. An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d(tvp)}$ = 200 ms, starts after V_{DD} has risen above the threshold voltage V_{IT}. When the supply voltage drops below the threshold voltage V_{IT}, the output becomes active (low) again. No external components are required. All the devices of this family have a fixed sense-threshold voltage V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23. The TPS3809 devices are characterized for operation over a temperature range of -40°C to 85°C.

Device Information

PART NUMBER	PACKAGE (1)	BODY SIZE (NOM)		
TPS3809	SOT-23 (3), DBV	2.90 mm × 1.60 mm		

For all available packages, see the orderable addendum at the end of the data sheet.



Typical Application



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4 Revision History

4 Revision history	
Changes from Revision C (October 2013) to Revision D (January 2021)	Page
 Updated the numbering format for tables, figures, and cross-references throughout the document 	1
Added new sentence regarding the new TLV809E to the <i>Description</i> section	1
Added the pinout and pin function table	4
Changed VDD from 7 to 6.5 in Absolute Maximum Ratings	5
 Changed V_{OL} @ 500μA from 0.2 to 0.3V and corrected header of the table from TPS3800-xx, TPS3801 TPS3802-xx to TPS3809xx in Electrical Characteristics 	-XX,
Changed t _w pulse duration from 3 to 10µs in <i>Timing Requirements</i>	6
• Changed t _{PHL} from 1 to 10µs in <i>Switching Characteristics</i>	6
Changes from Revision B (July 2012) to Revision C (October 2013)	Page
Changed front page and page flow to match current standard look and feel	1
• Changed "Operating junction temperature range" to "Operating free-air temperature range" in Absolute	
Maximum Ratings (typo)	5
Changes from Revision A (October 2010) to Revision B (July 2012)	Page
• Changed the Pull-up resistor value, RESET To: RESET current sink during startup in the Recommende	d
Operating Conditions Table	5
Changes from Revision * (August 1999) to Revision A (October 2010)	Page
Added Pull-up resistor value RESET to the Recommended Operating Conditions Table	-



5 Device Comparison

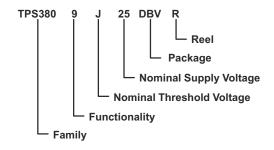
Table 5-1. Device Comparison Table

T _A	DEVICE NAME		THRESHOLD VOLTAGE	MARKING
-40°C to 85°C	TPS3809J25DBVR	TPS3809J25DBVT	2.25 V	PCZI
	TPS3809L30DBVR	TPS3809L30DBVT	2.64 V	PDAI
	TPS3809K33DBVR	TPS3809K33DBVT	2.93 V	PDBI
	TPS3809I50DBVR	TPS3809I50DBVT	4.55 V	PDCI

FUNCTION/TRUTH TABLE, TPS3809

V _{DD} >V _{IT}	RESET
0	L
1	Н

ORDERING INFORMATION





6 Pin Configuration and Functions

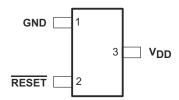


Figure 6-1. Pin configuration

Table 6-1. Pin Functions

PIN		I/O ⁽¹⁾	DESCRIPTION			
NAME	NO.	1,000	DESCRIPTION			
GND 1 -		-	This pin should be connected to ground with a low-impedance connection.			
RESET	RESET 2 O					
VDD 3		-	Supply voltage pin. A 0.1-µF ceramic capacitor from this pin to ground is recommended to improve stability of the threshold voltage			



7 Specifications

7.1 Absolute Maximum Ratings (1) (2)

Over operating free-air temperature range (unless otherwise noted).

	UNIT
Supply voltage, V _{DD}	6.5 V
All other pins	−0.3 V to 6.5 V
Maximum low-output current, I _{OL}	5 mA
Maximum high-output current, I _{OH}	−5 mA
Input-clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output-clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	-40°C to 85°C
Storage temperature range, T _{stg}	−65°C to 150°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 Recommended Operating Conditions

	MIN	MAX	UNIT
Supply voltage, V _{DD}	2	6	V
RESET current sink during startup		50	μΑ
Operating free-air temperature range, T _A	-40	+85	°C

7.3 Dissipation Ratings

PACKAGE $T_A < 25^{\circ}C$ DERATING FACTOR ABOVE $T_A < 25^{\circ}C$		T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

7.4 Electrical Characteristics

Over recommended operating free-air temperature range (unless otherwise noted).

PARAMETER			TEST CONDITIONS	TP	S3809xx			
PARA	AWEIEK		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
			$V_{DD} = 2.5 \text{ V to 6 V I}_{OH} = -500 \mu\text{A}$	V _{DD} -0.2				
V _{OH}	High-level output voltage	•	V _{DD} = 3.3 V I _{OH} = -2 mA	V _{DD} -0.4			V	
			V _{DD} = 6 V I _{OH} = –4 mA	V _{DD} -0.4				
			V _{DD} = 2 V to 6 V, I _{OL} = 500 μA			0.3		
V _{OL}	Low-level output voltage		V _{DD} = 3.3 V, I _{OL} = 2 mA			0.4	V	
			V _{DD} = 6 V, I _{OL} = 4 mA			0.4		
	Power-up reset voltage ⁽¹⁾		$V_{DD} \ge 1.1 \text{ V, } I_{OL} = 50 \mu\text{A}$			0.2	V	
		TPS3809J25	-T _A = -40°C to 85°C	2.2	2.25	2.3	V	
	Negative-going input	TPS3809L30		2.58	2.64	2.7		
V _{IT} _	threshold voltage ⁽²⁾	TPS3809K33		2.87	2.93	2.99		
		TPS3	TPS3809I50		4.45	4.55	4.65	
	Threshold hysteresis	TPS3809J25			30			
,		TPS3809L30			35		m)/	
V _{hys}		TPS3809K33	-		40		mV	
		TPS3809I50			60			

⁽²⁾ All voltage values are with respect to GND. For reliable operation, the device should not be operated at 6.5 V for more than t = 1000h continuously.



Over recommended operating free-air temperature range (unless otherwise noted).

PARAMETER		TEST CONDITIONS	TPS3809xx				
		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
I _{DD} Suppl	Supply current		V _{DD} = 2 V, output unconnected		9	12	^
	Supply current		V _{DD} = 6 V, output unconnected		20	25	μA
Ci	Input capacitance		V _I = 0 V to V _{DD}		5		pF

- (1) The lowest supply voltage at which \overline{RESET} becomes active. $t_{r, VDD} \ge 15 \mu s/V$.
- (2) To ensure the best stability of the threshold voltage, a bypass capacitor (0.1-µF ceramic) should be placed near the supply terminals.

7.5 Timing Requirements

at R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

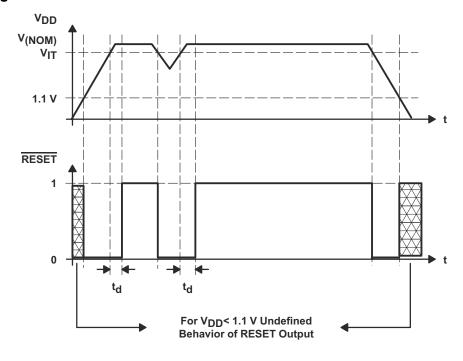
PAF	PARAMETER		TEST CONDITIONS		TYP	MAX	UNIT
t _w	Pulse width	at V _{DD}	$V_{DD} = V_{IT-} + 0.2 \text{ V}, V_{DD} = V_{IT-} -0.2 \text{ V}$	10			μs

7.6 Switching Characteristics

at $R_L = 1 M\Omega$, $C_L = 50 pF$, $T_A = 25$ °C

PARAI	METER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t _d	Delay time	V _{DD} ≥ V _{IT} + 0.2 V, See timing diagram	120	200	280	ms	
t _{PHL}	Propagation (delay) time, high-to-low-level output	V _{DD} to RESET delay	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$		10		μs

7.7 Timing Diagram





7.8 Typical Characteristics

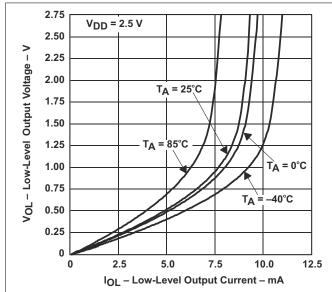


Figure 7-1. LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

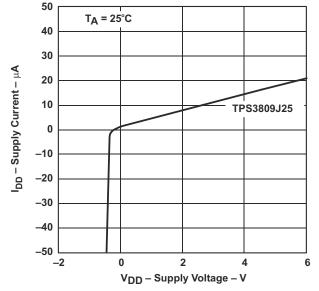


Figure 7-2. SUPPLY CURRENT vs SUPPLY VOLTAGE

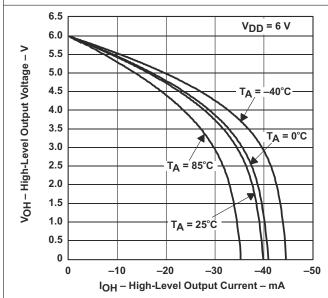


Figure 7-3. HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT at V_{DD}=6V

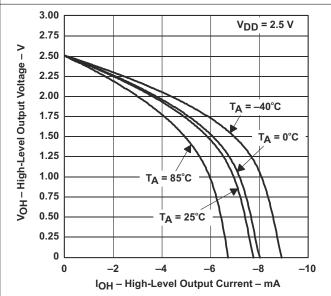
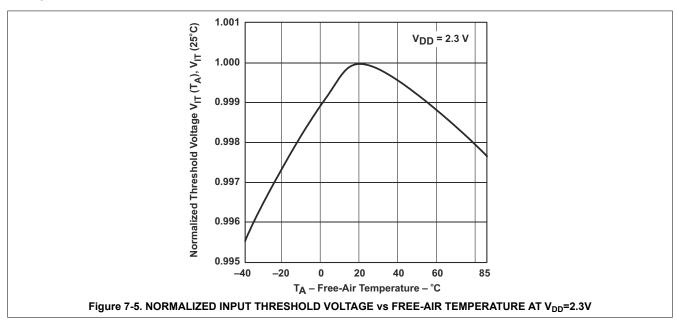


Figure 7-4. HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT at V_{DD} =2.5V

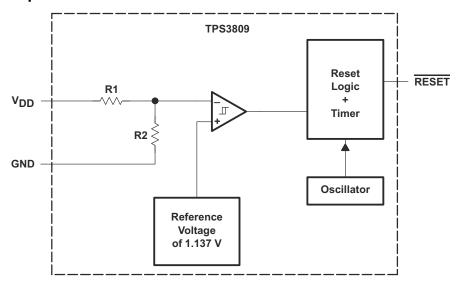


7.8 Typical Characteristics (continued)





8 Detailed Description



9 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
TPS3809I50DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809I50DBVR.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809I50DBVR1G4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809I50DBVR1G4.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809I50DBVRG4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TPS3809I50DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809I50DBVT.A	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI
TPS3809J25DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809J25DBVR.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809J25DBVRG4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809J25DBVRG4.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809J25DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809J25DBVT.A	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI
TPS3809K33DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809K33DBVR.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809K33DBVR1G4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809K33DBVR1G4.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809K33DBVRG4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TPS3809K33DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809K33DBVT.A	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI
TPS3809L30DBVR	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI
TPS3809L30DBVR.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI
TPS3809L30DBVR1G4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI
TPS3809L30DBVR1G4.A	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI
TPS3809L30DBVRG4	Active	Production	SOT-23 (DBV) 3	3000 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TPS3809L30DBVT	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI
TPS3809L30DBVT.A	Active	Production	SOT-23 (DBV) 3	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI

⁽¹⁾ Status: For more details on status, see our product life cycle.

PACKAGE OPTION ADDENDUM

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(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS3809:

Automotive : TPS3809-Q1

Enhanced Product: TPS3809-EP

NOTE: Qualified Version Definitions:

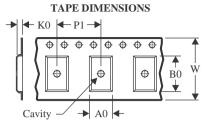
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications



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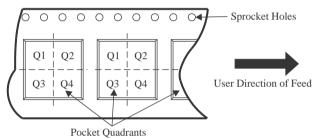
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

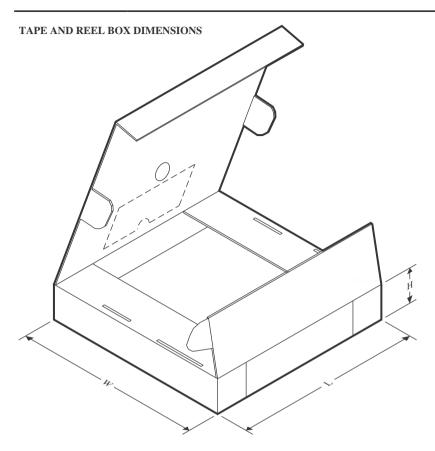


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3809I50DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809I50DBVR1G4	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809I50DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809J25DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809J25DBVRG4	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809J25DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809K33DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809K33DBVR1G4	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809K33DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809L30DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809L30DBVR1G4	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3809L30DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3



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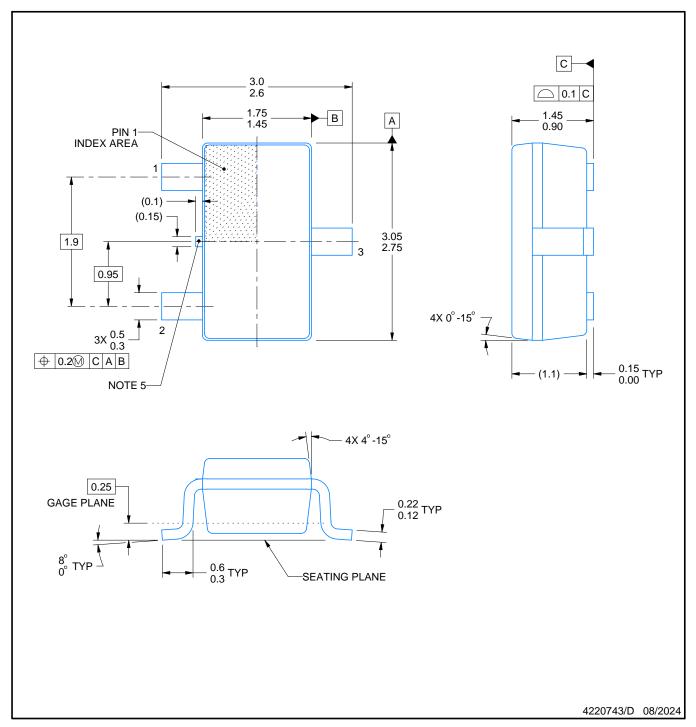


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3809I50DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809I50DBVR1G4	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809I50DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809J25DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809J25DBVRG4	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809J25DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809K33DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809K33DBVR1G4	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809K33DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809L30DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809L30DBVR1G4	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809L30DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0



SMALL OUTLINE TRANSISTOR



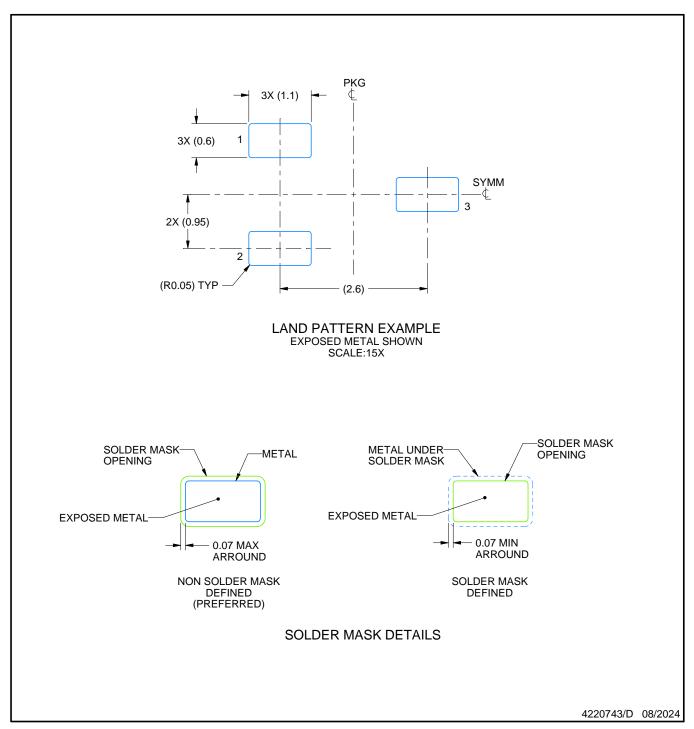
NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Refernce JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



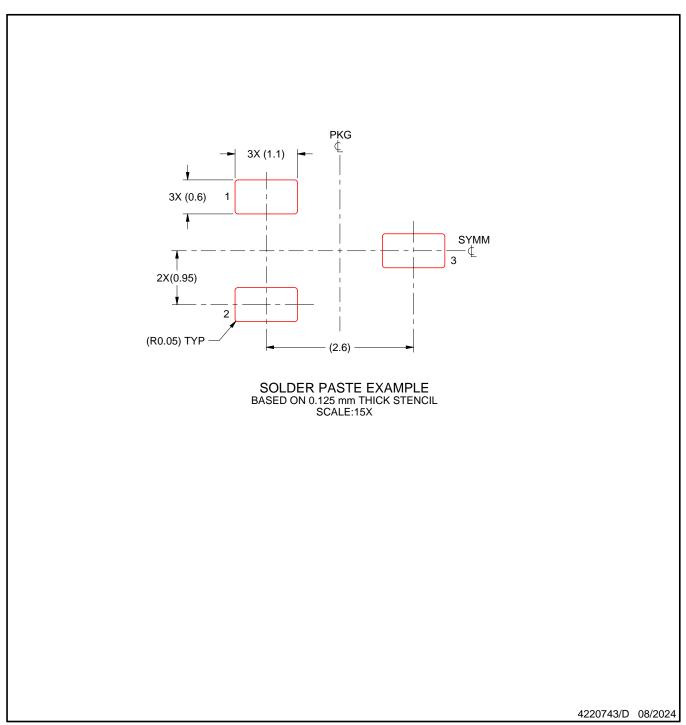
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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